STARPOWER

SEMICONDUCTOR

IGBT

GD300HFQ120C2S

1200V/300A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as electronic welder and inductive heating.

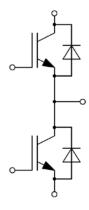
Features

- Low V_{CE(sat)} Trench IGBT technology
- 10μs short circuit capability
- V_{CE(sat)} with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Switching mode power supply
- Inductive heating
- Electronic welder

Equivalent Circuit Schematic



Absolute Maximum Ratings T_C =25°C unless otherwise noted

IGBT

Symbol	Description	Values	Unit	
V_{CES}	Collector-Emitter Voltage	1200	V	
V_{GES}	Gate-Emitter Voltage	±20	V	
$I_{\rm C}$	Collector Current @ T _C =25°C	434	A	
	@ T _C =90°C	300		
I_{CM}	Pulsed Collector Current t _p =1ms	600	Α	
P_{D}	Maximum Power Dissipation @ T _i =175°C	1612	W	

Diode

Symbol	Description	Values	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_{F}	Diode Continuous Forward Current	300	Α
I_{FM}	Diode Maximum Forward Current t _p =1ms	600	Α

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	°C
$T_{ m jop}$	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	4000	V

IGBT Characteristics $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
	Collector to Emitter Saturation Voltage	I_{C} =300A, V_{GE} =15V, T_{i} =25°C		1.85	2.25	
$V_{\text{CE}(\text{sat})}$		I _C =300A,V _{GE} =15V, T _i =125°C		2.40		V
	C	I _C =300A,V _{GE} =15V, T _i =150°C		2.50		
$V_{\text{GE(th)}}$	Gate-Emitter Threshold Voltage	I_C =7.50mA, V_{CE} = V_{GE} , T_i =25°C	5.2	6.0	6.8	V
I_{CES}	Collector Cut-Off Current	$V_{\text{CE}}=V_{\text{CES}}, V_{\text{GE}}=0V,$ $T_{\text{j}}=25^{\text{o}}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{\text{GE}}=V_{\text{GES}}, V_{\text{CE}}=0V,$ $T_{\text{j}}=25^{\circ}\text{C}$			100	nA
R _{Gint}	Internal Gate Resistance			2.5		Ω
Cies	Input Capacitance	N. OCNIC INCH		31.1		nF
C _{res}	Reverse Transfer Capacitance	V_{CE} =25V,f=1MHz, V_{GE} =0V		0.87		nF
Q_G	Gate Charge	V _{GE} =-15+15V		2.33		μC
t _{d(on)}	Turn-On Delay Time	02		240		ns
t_r	Rise Time	-		70		ns
t _{d(off)}	Turn-Off Delay Time			280		ns
$t_{\rm f}$	Fall Time	$V_{CC}=600V,I_{C}=300A,$		45		ns
E _{on}	Turn-On Switching Loss	R_{G} =1.6 Ω , V_{GE} =±15 V , T_{j} =25 $^{\circ}$ C		20.7		mJ
E _{off}	Turn-Off Switching Loss			16.5		mJ
f	Turn-On Delay Time			250		ns
$t_{d(on)}$ t_r	Rise Time	-		75		ns
	Turn-Off Delay Time	-		300		ns
t _{d(off)}	Fall Time	V_{CC} =600V, I_{C} =300A,		60		ns
$t_{\rm f}$ $E_{ m on}$	Turn-On Switching Loss	R_{G} =1.6 Ω , V_{GE} =±15 V , T_{j} =125 $^{\circ}$ C		29.4		mJ
$E_{ m off}$	Turn-Off Switching			19.1		mJ
-	Loss		1	261		
t _{d(on)}	Turn-On Delay Time	-		261		ns
t _r	Rise Time	V_{CC} =600V, I_{C} =300A, R_{G} =1.6 Ω , V_{GE} =±15V, T_{j} =150°C		79		ns
t _{d(off)}	Turn-Off Delay Time			320		ns
$t_{\rm f}$	Fall Time			65		ns
E _{on}	Turn-On Switching Loss			32.4		mJ
E_{off}	Turn-Off Switching Loss			21.0		mJ

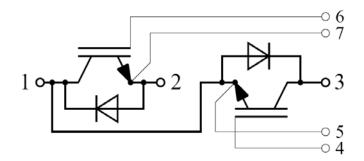
Diode Characteristics $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V_{F}	Diode Forward Voltage	$I_F = 300A, V_{GE} = 0V, T_i = 25^{\circ}C$		1.90	2.35	V
		$I_F=300A, V_{GE}=0V, T_j=125^{\circ}C$		1.90		
	voltage	$I_F = 300A, V_{GE} = 0V, T_i = 150^{\circ}C$		1.90		
Q_{r}	Recovered			24		μC
Q r	Charge	$V_{R}=600V,I_{F}=300A,$		24		μ
I_{RM}	Peak Reverse	$-di/dt=5220A/\mu s, V_{GE}=-15V$		460		Α
1RM	Recovery Current	$T_i=25^{\circ}C$		400		А
E_{rec}	Reverse Recovery	1 _j -25 C		12.0		mJ
rec	Energy					
Q_{r}	Recovered	$\begin{array}{c} V_{R}\!\!=\!\!600V,\!I_{F}\!\!=\!\!300A,\\ -di/dt\!\!=\!\!5220A/\mu s,\!V_{GE}\!\!=\!\!-15V\\ T_{j}\!\!=\!\!125^{\circ}\!C \end{array}$		42.8		μC
Q r	Charge			72.0		μ
I_{RM}	Peak Reverse			502		A
1RM	Recovery Current			302		71
E_{rec}	Reverse Recovery			19.6		mJ
rec	Energy			17.0		1113
$Q_{\rm r}$	Recovered			47.8		μC
Q r	Charge	V_R =600V, I_F =300A, -di/dt=5220A/ μ s, V_{GE} =-15V T_i =150°C		47.0		μ
I_{RM}	Peak Reverse			524		Α
	Recovery Current			324		11
E _{rec}	Reverse Recovery	1,-150 €		23.0		mJ
	Energy			23.0		1113

Module Characteristics $T_C=25^{\circ}C$ unless otherwise noted

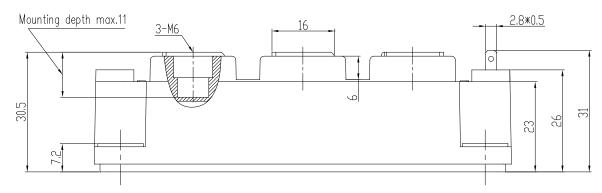
Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance			20	nΗ
R _{CC'+EE'}	Module Lead Resistance, Terminal to Chip		0.35		$m\Omega$
D	Junction-to-Case (per IGBT)			0.093	K/W
R_{thJC}	Junction-to-Case (per Diode)			0.115	IX/ VV
	Case-to-Heatsink (per IGBT)		0.036		
R_{thCH}	Case-to-Heatsink (per Diode)		0.045		K/W
	Case-to-Heatsink (per Module)		0.010		
M	Terminal Connection Torque, Screw M6	2.5		5.0	N.m
	Mounting Torque, Screw M6	3.0		5.0	11.111
G	Weight of Module		300		g

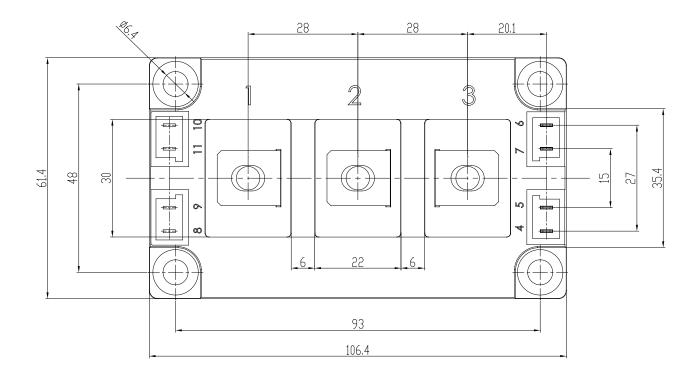
Circuit Schematic



Package Dimensions

Dimensions in Millimeters





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